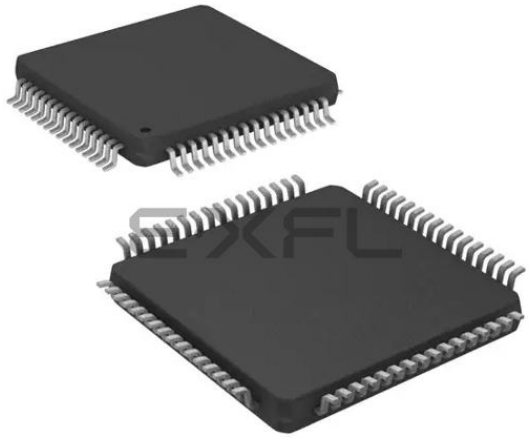

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	16MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	50
Program Memory Size	16KB (8K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	454 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic17c752-16-pt

TABLE 1-1: PIC17CXXX FAMILY OF DEVICES

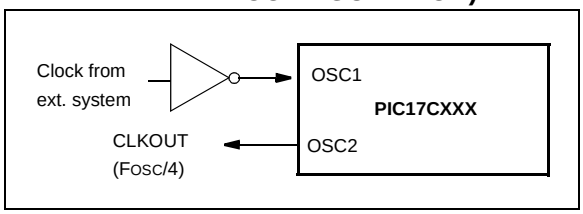
Features		PIC17C42A	PIC17C43	PIC17C44	PIC17C752	PIC17C756A	PIC17C762	PIC17C766
Maximum Frequency of Operation		33 MHz	33 MHz	33 MHz	33 MHz	33 MHz	33 MHz	33 MHz
Operating Voltage Range		2.5 - 6.0V	2.5 - 6.0V	2.5 - 6.0V	3.0 - 5.5V	3.0 - 5.5V	3.0 - 5.5V	3.0 - 5.5V
Program Memory (x16)	(EPROM)	2 K	4 K	8 K	8 K	16 K	8 K	16 K
	(ROM)	—	—	—	—	—	—	—
Data Memory (bytes)		232	454	454	678	902	678	902
Hardware Multiplier (8 x 8)		Yes	Yes	Yes	Yes	Yes	Yes	Yes
Timer0 (16-bit + 8-bit postscaler)		Yes	Yes	Yes	Yes	Yes	Yes	Yes
Timer1 (8-bit)		Yes	Yes	Yes	Yes	Yes	Yes	Yes
Timer2 (8-bit)		Yes	Yes	Yes	Yes	Yes	Yes	Yes
Timer3 (16-bit)		Yes	Yes	Yes	Yes	Yes	Yes	Yes
Capture inputs (16-bit)		2	2	2	4	4	4	4
PWM outputs (up to 10-bit)		2	2	2	3	3	3	3
USART/SCI		1	1	1	2	2	2	2
A/D channels (10-bit)		—	—	—	12	12	16	16
SSP (SPI/I^2C w/Master mode)		—	—	—	Yes	Yes	Yes	Yes
Power-on Reset		Yes	Yes	Yes	Yes	Yes	Yes	Yes
Watchdog Timer		Yes	Yes	Yes	Yes	Yes	Yes	Yes
External Interrupts		Yes	Yes	Yes	Yes	Yes	Yes	Yes
Interrupt Sources		11	11	11	18	18	18	18
Code Protect		Yes	Yes	Yes	Yes	Yes	Yes	Yes
Brown-out Reset		—	—	—	Yes	Yes	Yes	Yes
In-Circuit Serial Programming		—	—	—	Yes	Yes	Yes	Yes
I/O Pins		33	33	33	50	50	66	66
I/O High Current Capability	Source	25 mA	25 mA	25 mA	25 mA	25 mA	25 mA	25 mA
	Sink	25 mA(1)	25 mA(1)	25 mA(1)	25 mA(1)	25 mA(1)	25 mA(1)	25 mA(1)
Package Types		40-pin DIP 44-pin PLCC 44-pin MQFP 44-pin TQFP	40-pin DIP 44-pin PLCC 44-pin MQFP 44-pin TQFP	40-pin DIP 44-pin PLCC 44-pin MQFP 44-pin TQFP	64-pin TQFP 68-pin PLCC	64-pin TQFP 68-pin PLCC	80-pin TQFP 84-pin PLCC	80-pin TQFP 84-pin PLCC

Note 1: Pins RA2 and RA3 can sink up to 60 mA.

4.1.4 EXTERNAL CLOCK OSCILLATOR

In the EC oscillator mode, the OSC1 input can be driven by CMOS drivers. In this mode, the OSC1/CLKIN pin is hi-impedance and the OSC2/CLKOUT pin is the CLKOUT output (4 TOSC).

FIGURE 4-4: EXTERNAL CLOCK INPUT OPERATION (EC OSC CONFIGURATION)



4.1.5 EXTERNAL CRYSTAL OSCILLATOR CIRCUIT

Either a prepackaged oscillator can be used, or a simple oscillator circuit with TTL gates can be built. Prepackaged oscillators provide a wide operating range and better stability. A well designed crystal oscillator will provide good performance with TTL gates. Two types of crystal oscillator circuits can be used: one with series resonance, or one with parallel resonance.

Figure 4-5 shows implementation of a parallel resonant oscillator circuit. The circuit is designed to use the fundamental frequency of the crystal. The 74AS04 inverter performs the 180-degree phase shift that a parallel oscillator requires. The 4.7 kΩ resistor provides the negative feedback for stability. The 10 kΩ potentiometer biases the 74AS04 in the linear region. This could be used for external oscillator designs.

FIGURE 4-5: EXTERNAL PARALLEL RESONANT CRYSTAL OSCILLATOR CIRCUIT

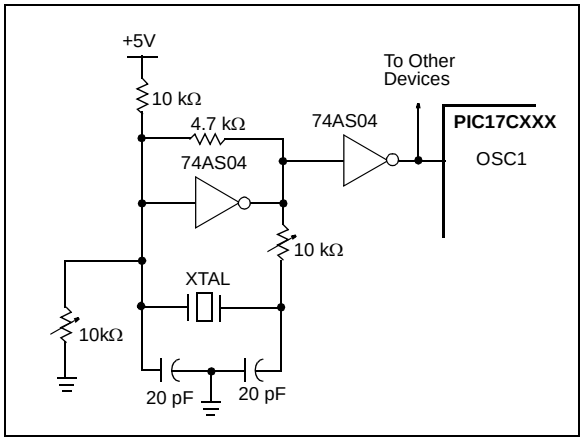
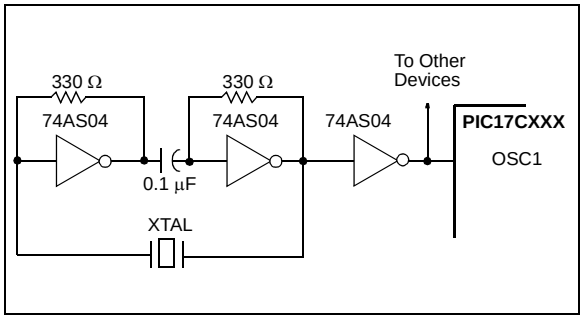


Figure 4-6 shows a series resonant oscillator circuit. This circuit is also designed to use the fundamental frequency of the crystal. The inverter performs a 180-degree phase shift in a series resonant oscillator circuit. The 330 Ω resistors provide the negative feedback to bias the inverters in their linear region.

FIGURE 4-6: EXTERNAL SERIES RESONANT CRYSTAL OSCILLATOR CIRCUIT



NOTES:

REGISTER 6-5: PIR2 REGISTER (ADDRESS: 10h, BANK 4)

R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R-1	R-0
SSPIF	BCLIF	ADIF	—	CA4IF	CA3IF	TX2IF	RC2IF
bit 7							bit 0

bit 7 **SSPIF**: Synchronous Serial Port (SSP) Interrupt Flag bit
1 = The SSP interrupt condition has occurred and must be cleared in software before returning from the Interrupt Service Routine. The conditions that will set this bit are:

SPI:
A transmission/reception has taken place.

I^2C Slave/Master:
A transmission/reception has taken place.

I^2C Master:
The initiated START condition was completed by the SSP module.
The initiated STOP condition was completed by the SSP module.
The initiated Restart condition was completed by the SSP module.
The initiated Acknowledge condition was completed by the SSP module.
A START condition occurred while the SSP module was idle (Multi-master system).
A STOP condition occurred while the SSP module was idle (Multi-master system).

0 = An SSP interrupt condition has NOT occurred

bit 6 **BCLIF**: Bus Collision Interrupt Flag bit
1 = A bus collision has occurred in the SSP, when configured for I^2C Master mode
0 = No bus collision has occurred

bit 5 **ADIF**: A/D Module Interrupt Flag bit
1 = An A/D conversion is complete
0 = An A/D conversion is not complete

bit 4 **Unimplemented**: Read as '0'

bit 3 **CA4IF**: Capture4 Interrupt Flag bit
1 = Capture event occurred on RE3/CAP4 pin
0 = Capture event did not occur on RE3/CAP4 pin

bit 2 **CA3IF**: Capture3 Interrupt Flag bit
1 = Capture event occurred on RG4/CAP3 pin
0 = Capture event did not occur on RG4/CAP3 pin

bit 1 **TX2IF**:USART2 Transmit Interrupt Flag bit (state controlled by hardware)
1 = USART2 Transmit buffer is empty
0 = USART2 Transmit buffer is full

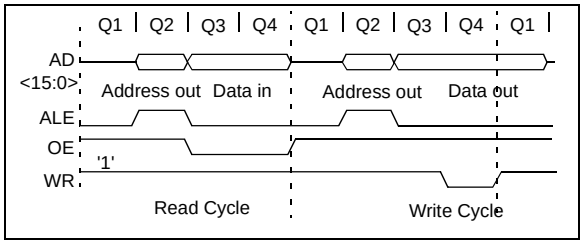
bit 0 **RC2IF**: USART2 Receive Interrupt Flag bit (state controlled by hardware)
1 = USART2 Receive buffer is full
0 = USART2 Receive buffer is empty

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
- n = Value at POR Reset	’1’ = Bit is set	’0’ = Bit is cleared	x = Bit is unknown

7.1.2 EXTERNAL MEMORY INTERFACE

When either Microprocessor or Extended Microcontroller mode is selected, PORTC, PORTD and PORTE are configured as the system bus. PORTC and PORTD are the multiplexed address/data bus and PORTE<2:0> is for the control signals. External components are needed to demultiplex the address and data. This can be done as shown in Figure 7-4. The waveforms of address and data are shown in Figure 7-3. For complete timings, please refer to the electrical specification section.

FIGURE 7-3: EXTERNAL PROGRAM MEMORY ACCESS WAVEFORMS



The system bus requires that there is no bus conflict (minimal leakage), so the output value (address) will be capacitively held at the desired value.

As the speed of the processor increases, external EPROM memory with faster access time must be used. Table 7-2 lists external memory speed requirements for a given PIC17C7XX device frequency.

In Extended Microcontroller mode, when the device is executing out of internal memory, the control signals will continue to be active. That is, they indicate the action that is occurring in the internal memory. The external memory access is ignored.

The following selection is for use with Microchip EPROMs. For interfacing to other manufacturers memory, please refer to the electrical specifications of the desired PIC17C7XX device, as well as the desired memory device to ensure compatibility.

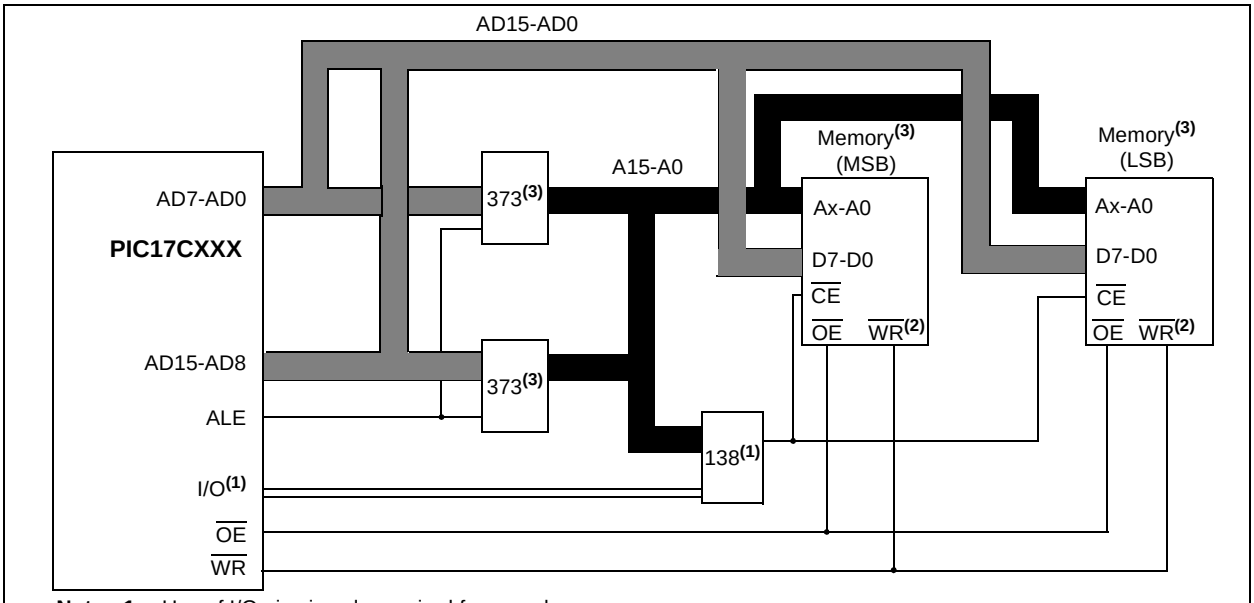
TABLE 7-2: EPROM MEMORY ACCESS TIME ORDERING SUFFIX

PIC17C7XX Oscillator Frequency	Instruction Cycle Time (TCY)	EPROM Suffix
8 MHz	500 ns	-25
16 MHz	250 ns	-15
20 MHz	200 ns	-10
25 MHz	160 ns	-70

Note: The access times for this requires the use of fast SRAMs.

The electrical specifications now include timing specifications for the memory interface with PIC17**LC**XXX devices. These specifications reflect the capability of the device by characterization. Please validate your design with these timings.

FIGURE 7-4: TYPICAL EXTERNAL PROGRAM MEMORY CONNECTION DIAGRAM



Note 1: Use of I/O pins is only required for paged memory.
2: This signal is unused for ROM and EPROM devices.
3: 16-bit wide devices are now common and could be used instead of 8-bit wide devices.

NOTES:

10.0 I/O PORTS

PIC17C75X devices have seven I/O ports, PORTA through PORTG. PIC17C76X devices have nine I/O ports, PORTA through PORTJ. PORTB through PORTJ have a corresponding Data Direction Register (DDR), which is used to configure the port pins as inputs or outputs. Some of these ports pins are multiplexed with alternate functions.

PORTC, PORTD, and PORTE are multiplexed with the system bus. These pins are configured as the system bus when the device's configuration bits are selected to Microprocessor or Extended Microcontroller modes. In the two other microcontroller modes, these pins are general purpose I/O.

PORTA, PORTB, PORTE<3>, PORTF, PORTG and the upper four bits of PORTH are multiplexed with the peripheral features of the device. These peripheral features are:

- Timer Modules
- Capture Modules
- PWM Modules
- USART/SCI Modules
- SSP Module
- A/D Module
- External Interrupt pin

When some of these peripheral modules are turned on, the port pin will automatically configure to the alternate function. The modules that do this are:

- PWM Module
- SSP Module
- USART/SCI Module

When a pin is automatically configured as an output by a peripheral module, the pins data direction (DDR) bit is unknown. After disabling the peripheral module, the user should re-initialize the DDR bit to the desired configuration.

The other peripheral modules (which require an input) must have their data direction bits configured appropriately.

Note:	A pin that is a peripheral input, can be configured as an output (DDRx<y> is cleared). The peripheral events will be determined by the action output on the port pin.

When the device enters the "RESET state", the Data Direction registers (DDR) are forced set, which will make the I/O hi-impedance inputs. The RESET state of some peripheral modules may force the I/O to other operations, such as analog inputs or the system bus.

13.1.2 TIMER1 AND TIMER2 IN 16-BIT MODE

To select 16-bit mode, set the T16 bit. In this mode, TMR2 and TMR1 are concatenated to form a 16-bit timer (TMR2:TMR1). The 16-bit timer increments until it matches the 16-bit period register (PR2:PR1). On the following timer clock, the timer value is reset to 0h, and the TMR1IF bit is set.

When selecting the clock source for the 16-bit timer, the TMR1CS bit controls the entire 16-bit timer and TMR2CS is a “don’t care”, however, ensure that TMR2ON is set (allows TMR2 to increment). When TMR1CS is clear, the timer increments once every instruction cycle (FOSC/4). When TMR1CS is set, the timer increments on every falling edge of the RB4/TCLK12 pin. For the 16-bit timer to increment, both TMR1ON and TMR2ON bits must be set (Table 13-2).

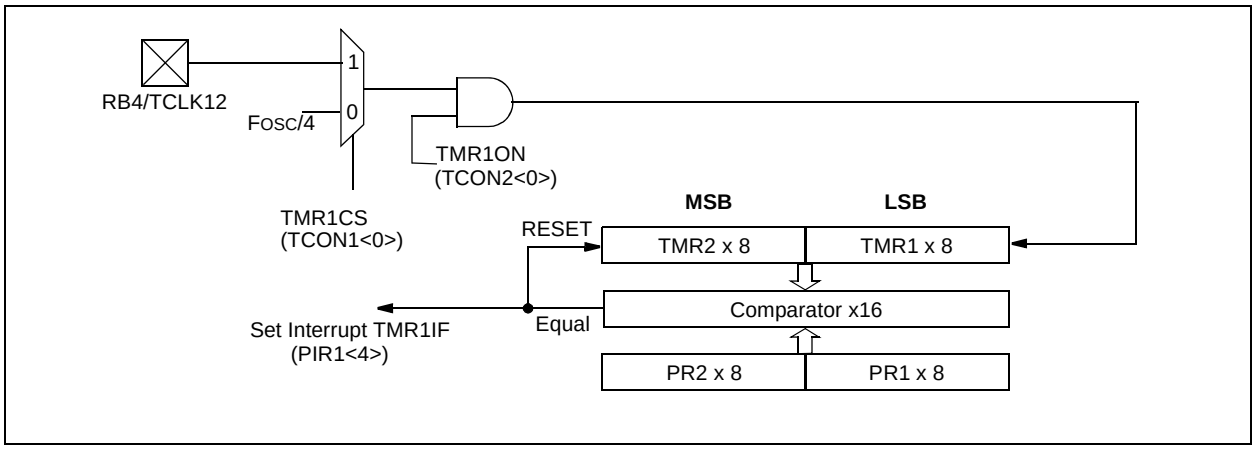
13.1.2.1 External Clock Input for TMR2:TMR1

When TMR1CS is set, the 16-bit TMR2:TMR1 increments on the falling edge of clock input TCLK12. The input on the RB4/TCLK12 pin is sampled and synchronized by the internal phase clocks twice every instruction cycle. This causes a delay from the time a falling edge appears on RB4/TCLK12 to the time TMR2:TMR1 is actually incremented. For the external clock input timing requirements, see the Electrical Specification section.

TABLE 13-2: TURNING ON 16-BIT TIMER

T16	TMR2ON	TMR1ON	Result
1	1	1	16-bit timer (TMR2:TMR1) ON
1	0	1	Only TMR1 increments
1	x	0	16-bit timer OFF
0	1	1	Timers in 8-bit mode

FIGURE 13-2: TMR2 AND TMR1 IN 16-BIT TIMER/COUNTER MODE



13.1.3.3 External Clock Source

The PWMs will operate, regardless of the clock source of the timer. The use of an external clock has ramifications that must be understood. Because the external TCLK12 input is synchronized internally (sampled once per instruction cycle), the time TCLK12 changes to the time the timer increments, will vary by as much as 1TCY (one instruction cycle). This will cause jitter in the duty cycle as well as the period of the PWM output.

This jitter will be ±1TCY, unless the external clock is synchronized with the processor clock. Use of one of the PWM outputs as the clock source to the TCLK12 input, will supply a synchronized clock.

In general, when using an external clock source for PWM, its frequency should be much less than the device frequency (FOSC).

13.1.3.4 Maximum Resolution/Frequency for External Clock Input

The use of an external clock for the PWM time base (Timer1 or Timer2) limits the PWM output to a maximum resolution of 8-bits. The PWxDCL<7:6> bits must be kept cleared. Use of any other value will distort the PWM output. All resolutions are supported when internal clock mode is selected. The maximum attainable frequency is also lower. This is a result of the timing requirements of an external clock input for a timer (see the Electrical Specification section). The maximum PWM frequency, when the timers clock source is the RB4/TCLK12 pin, is shown in Table 13-4 (Standard Resolution mode).

TABLE 13-5: REGISTERS/BITS ASSOCIATED WITH PWM

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	$\overline{\text{MCLR}}$, WDT
16h, Bank 3	TCON1	CA2ED1	CA2ED0	CA1ED1	CA1ED0	T16	TMR3CS	TMR2CS	TMR1CS	0000 0000	0000 0000
17h, Bank 3	TCON2	CA2OVF	CA1OVF	PWM2ON	PWM1ON	CA1/$\overline{\text{PR3}}$	TMR3ON	TMR2ON	TMR1ON	0000 0000	0000 0000
16h, Bank 7	TCON3	—	CA4OVF	CA3OVF	CA4ED1	CA4ED0	CA3ED1	CA3ED0	PWM3ON	-000 0000	-000 0000
10h, Bank 2	TMR1	Timer1's Register								xxxx xxxx	uuuu uuuu
11h, Bank 2	TMR2	Timer2's Register								xxxx xxxx	uuuu uuuu
16h, Bank 1	PIR1	RBIF	TMR3IF	TMR2IF	TMR1IF	CA2IF	CA1IF	TX1IF	RC1IF	x000 0010	u000 0010
17h, Bank 1	PIE1	RBIE	TMR3IE	TMR2IE	TMR1IE	CA2IE	CA1IE	TX1IE	RC1IE	0000 0000	0000 0000
07h, Unbanked	INTSTA	PEIF	T0CKIF	T0IF	INTF	PEIE	T0CKIE	T0IE	INTE	0000 0000	0000 0000
06h, Unbanked	CPUSTA	—	—	STKAV	GLINTD	$\overline{\text{TO}}$	$\overline{\text{PD}}$	POR	BOR	--11 11qq	--11 qquu
14h, Bank 2	PR1	Timer1 Period Register								xxxx xxxx	uuuu uuuu
15h, Bank 2	PR2	Timer2 Period Register								xxxx xxxx	uuuu uuuu
10h, Bank 3	PW1DCL	DC1	DC0	—	—	—	—	—	—	xx-- ----	uu-- ----
11h, Bank 3	PW2DCL	DC1	DC0	TM2PW2	—	—	—	—	—	xx0- ----	uu0- ----
10h, Bank 7	PW3DCL	DC1	DC0	TM2PW3	—	—	—	—	—	xx0- ----	uu0- ----
12h, Bank 3	PW1DCH	DC9	DC8	DC7	DC6	DC5	DC4	DC3	DC2	xxxx xxxx	uuuu uuuu
13h, Bank 3	PW2DCH	DC9	DC8	DC7	DC6	DC5	DC4	DC3	DC2	xxxx xxxx	uuuu uuuu
11h, Bank 7	PW3DCH	DC9	DC8	DC7	DC6	DC5	DC4	DC3	DC2	xxxx xxxx	uuuu uuuu

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0', q = value depends on conditions.
Shaded cells are not used by PWM Module.

13.2.3 READING THE CAPTURE REGISTERS

The Capture overflow status flag bits are double buffered. The master bit is set if one captured word is already residing in the Capture register and another "event" has occurred on the CAPx pin. The new event will not transfer the TMR3 value to the capture register, protecting the previous unread capture value. When the user reads both the high and the low bytes (in any order) of the Capture register, the master overflow bit is transferred to the slave overflow bit (CAxOVF) and then the master bit is reset. The user can then read TCONx to determine the value of CAxOVF.

An example of an instruction sequence to read capture registers and capture overflow flag bits is shown in Example 13-1. Depending on the capture source, different registers will need to be read.

EXAMPLE 13-1: SEQUENCE TO READ CAPTURE REGISTERS

```
MOVLB 3                  ; Select Bank 3
MOVPF CA2L, LO_BYTE      ; Read Capture2 low byte, store in LO_BYTE
MOVPF CA2H, HI_BYTE      ; Read Capture2 high byte, store in HI_BYTE
MOVPF TCON2, STAT_VAL    ; Read TCON2 into file STAT_VAL
```

TABLE 13-6: REGISTERS ASSOCIATED WITH CAPTURE

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	$\overline{MCLR}$, WDT
16h, Bank 3	TCON1	CA2ED1	CA2ED0	CA1ED1	CA1ED0	T16	TMR3CS	TMR2CS	TMR1CS	0000 0000	0000 0000
17h, Bank 3	TCON2	CA2OVF	CA1OVF	PWM2ON	PWM1ON	CA1/$\overline{PR3}$	TMR3ON	TMR2ON	TMR1ON	0000 0000	0000 0000
16h, Bank 7	TCON3	—	CA4OVF	CA3OVF	CA4ED1	CA4ED0	CA3ED1	CA3ED0	PWM3ON	-000 0000	-000 0000
12h, Bank 2	TMR3L	Holding Register for the Low Byte of the 16-bit TMR3 Register								xxxx xxxx	uuuu uuuu
13h, Bank 2	TMR3H	Holding Register for the High Byte of the 16-bit TMR3 Register								xxxx xxxx	uuuu uuuu
16h, Bank 1	PIR1	RBIF	TMR3IF	TMR2IF	TMR1IF	CA2IF	CA1IF	TX1IF	RC1IF	x000 0010	u000 0010
17h, Bank 1	PIE1	RBIE	TMR3IE	TMR2IE	TMR1IE	CA2IE	CA1IE	TX1IE	RC1IE	0000 0000	0000 0000
10h, Bank 4	PIR2	SSPIF	BCLIF	ADIF	—	CA4IF	CA3IF	TX2IF	RC2IF	000- 0010	000- 0010
11h, Bank 4	PIE2	SSPIE	BCLIE	ADIE	—	CA4IE	CA3IE	TX2IE	RC2IE	000- 0000	000- 0000
07h, Unbanked	INTSTA	PEIF	T0CKIF	T0IF	INTF	PEIE	T0CKIE	T0IE	INTE	0000 0000	0000 0000
06h, Unbanked	CPUSTA	—	—	STKAV	GLINTD	$\overline{TO}$	$\overline{PD}$	$\overline{POR}$	$\overline{BOR}$	--11 11qq	--11 qquu
16h, Bank 2	PR3L/CA1L	Timer3 Period Register, Low Byte/Capture1 Register, Low Byte								xxxx xxxx	uuuu uuuu
17h, Bank 2	PR3H/CA1H	Timer3 Period Register, High Byte/Capture1 Register, High Byte								xxxx xxxx	uuuu uuuu
14h, Bank 3	CA2L	Capture2 Low Byte								xxxx xxxx	uuuu uuuu
15h, Bank 3	CA2H	Capture2 High Byte								xxxx xxxx	uuuu uuuu
12h, Bank 7	CA3L	Capture3 Low Byte								xxxx xxxx	uuuu uuuu
13h, Bank 7	CA3H	Capture3 High Byte								xxxx xxxx	uuuu uuuu
14h, Bank 7	CA4L	Capture4 Low Byte								xxxx xxxx	uuuu uuuu
15h, Bank 7	CA4H	Capture4 High Byte								xxxx xxxx	uuuu uuuu

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0', q = value depends on condition.
Shaded cells are not used by Capture.

15.2 MSSP I²C Operation

The MSSP module in I²C mode fully implements all master and slave functions (including general call support) and provides interrupts on START and STOP bits in hardware to determine a free bus (multi-master function). The MSSP module implements the standard mode specifications as well as 7-bit and 10-bit addressing.

Refer to Application Note AN578, *"Use of the SSP Module in the I²C Multi-Master Environment."*

A "glitch" filter is on the SCL and SDA pins when the pin is an input. This filter operates in both the 100 kHz and 400 kHz modes. In the 100 kHz mode, when these pins are an output, there is a slew rate control of the pin that is independent of device frequency.

FIGURE 15-10: I²C SLAVE MODE BLOCK DIAGRAM

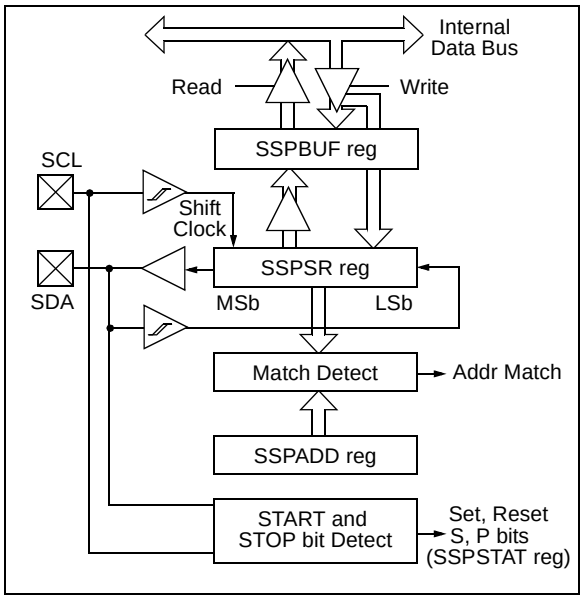
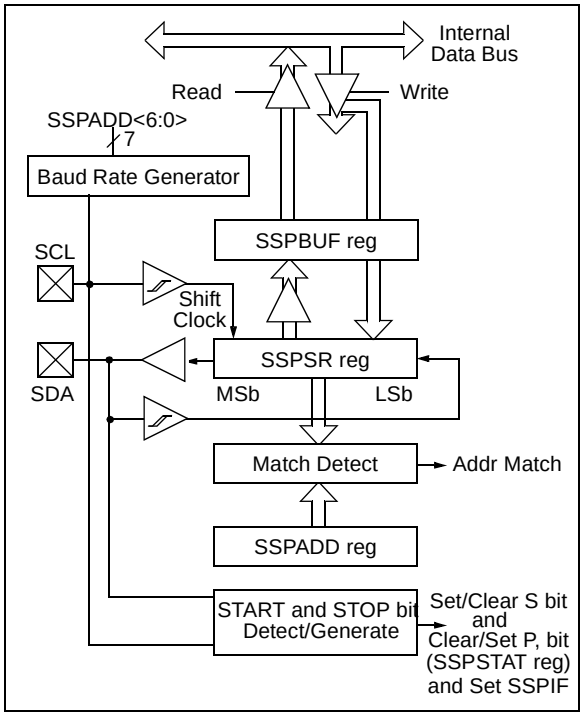


FIGURE 15-11: I²C MASTER MODE BLOCK DIAGRAM



Two pins are used for data transfer. These are the SCL pin, which is the clock and the SDA pin, which is the data. The SDA and SCL pins are automatically configured when the I²C mode is enabled. The SSP module functions are enabled by setting SSP Enable bit SSPEN (SSPCON1<5>).

The MSSP module has six registers for I²C operation. These are the:

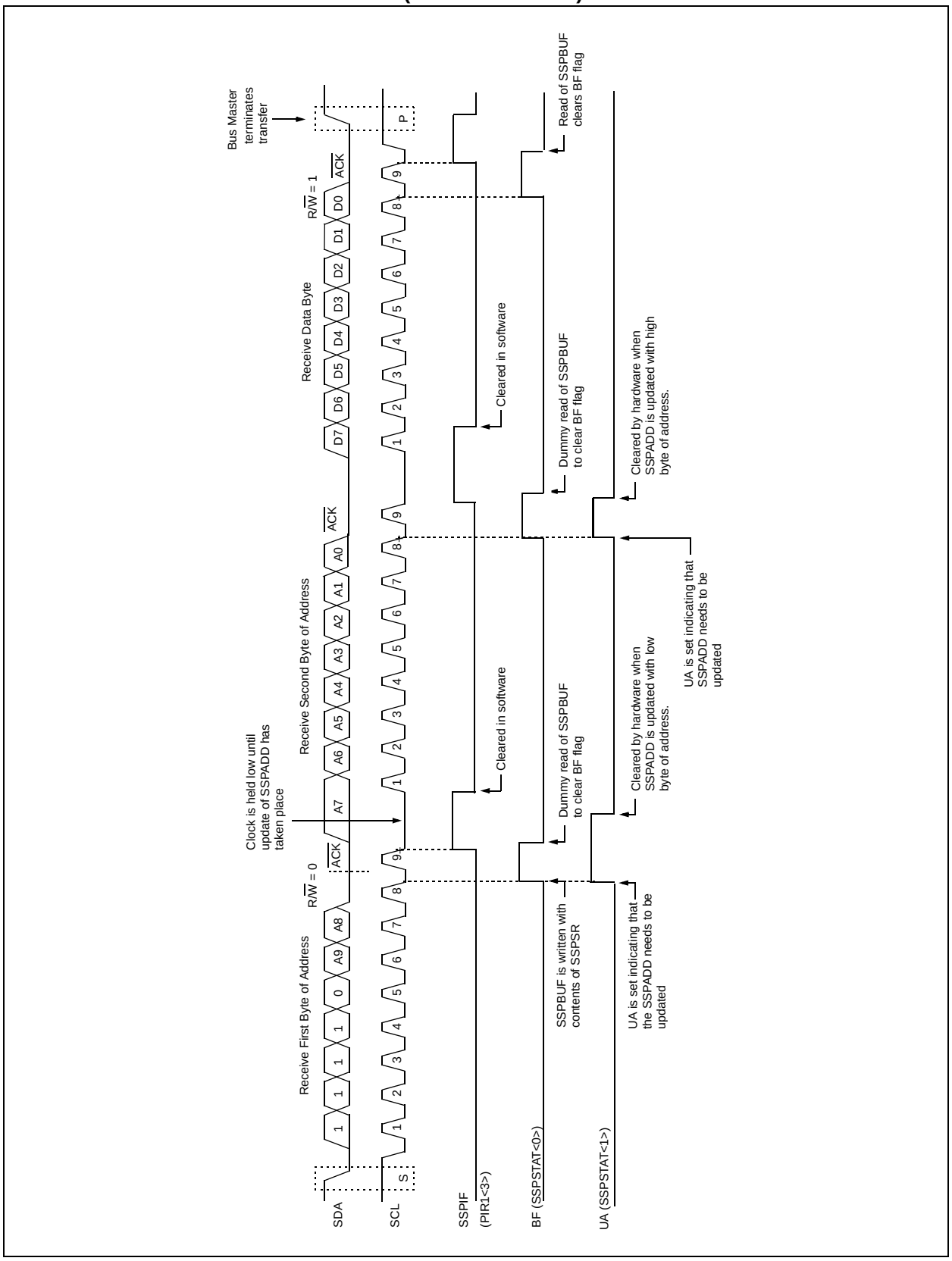
- SSP Control Register1 (SSPCON1)
- SSP Control Register2 (SSPCON2)
- SSP Status Register (SSPSTAT)
- Serial Receive/Transmit Buffer (SSPBUF)
- SSP Shift Register (SSPSR) - Not directly accessible
- SSP Address Register (SSPADD)

The SSPCON1 register allows control of the I²C operation. Four mode selection bits (SSPCON1<3:0>) allow one of the following I²C modes to be selected:

- I²C Slave mode (7-bit address)
- I²C Slave mode (10-bit address)
- I²C Master mode, clock = OSC/4 (SSPADD +1)

Before selecting any I²C mode, the SCL and SDA pins must be programmed to inputs by setting the appropriate DDR bits. Selecting an I²C mode, by setting the SSPEN bit, enables the SCL and SDA pins to be used as the clock and data lines in I²C mode.

FIGURE 15-15: I^2C SLAVE-RECEIVER (10-BIT ADDRESS)



15.2.5 MASTER MODE

Master mode of operation is supported by interrupt generation on the detection of the START and STOP conditions. The STOP (P) and START (S) bits are cleared from a RESET, or when the MSSP module is disabled. Control of the I^2C bus may be taken when the P bit is set, or the bus is idle, with both the S and P bits clear.

In Master mode, the SCL and SDA lines are manipulated by the MSSP hardware.

The following events will cause SSP Interrupt Flag bit, SSPIF, to be set (SSP Interrupt if enabled):

- START condition
- STOP condition
- Data transfer byte transmitted/received
- Acknowledge transmit
- Repeated Start

FIGURE 15-17: SSP BLOCK DIAGRAM (I^2C MASTER MODE)

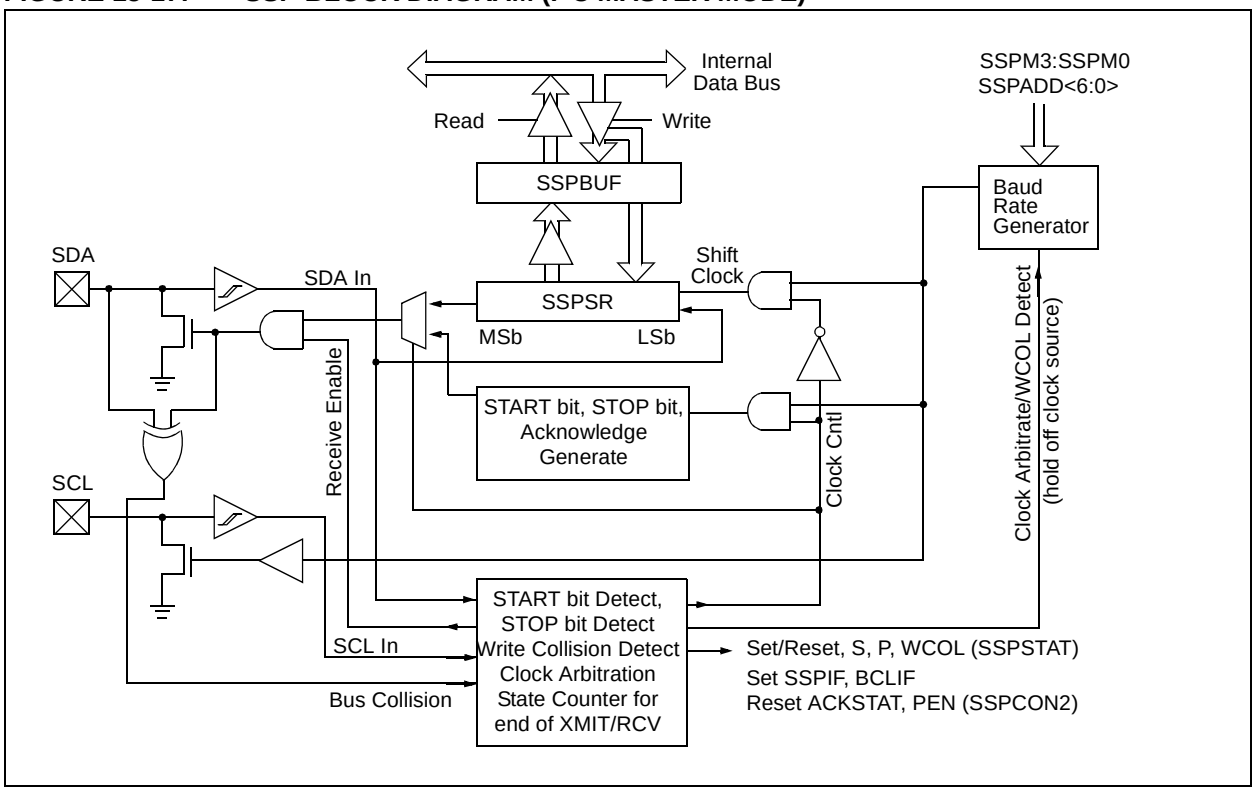
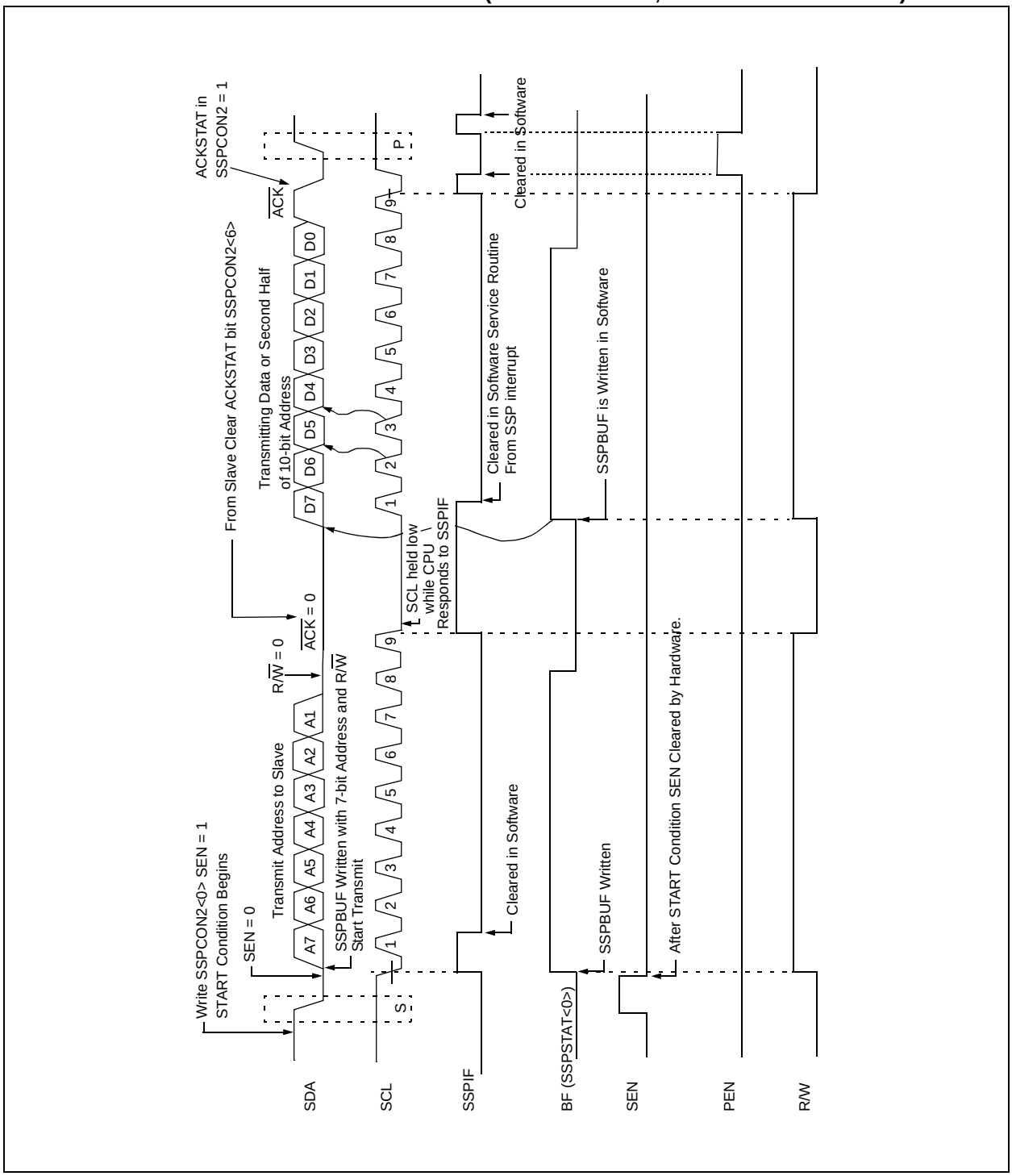


FIGURE 15-26: I²C MASTER MODE TIMING (TRANSMISSION, 7 OR 10-BIT ADDRESS)



CALL **Subroutine Call**

Syntax: [*label*] CALL k

Operands: $0 \le k \le 8191$

Operation: PC+ 1→ TOS, k → PC<12:0>, k<12:8> → PCLATH<4:0>; PC<15:13> → PCLATH<7:5>

Status Affected: None

Encoding:

111k	kkkk	kkkk	kkkk

Description: Subroutine call within 8K page. First, return address (PC+1) is pushed onto the stack. The 13-bit value is loaded into PC bits<12:0>. Then the upper-eight bits of the PC are copied into PCLATH. CALL is a two-cycle instruction.

See LCALL for calls outside 8K memory space.

Words: 1

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'<7:0>, Push PC to stack	Process Data	Write to PC
No operation	No operation	No operation	No operation

Example: HERE CALL THERE

Before Instruction
PC = Address (HERE)

After Instruction
PC = Address (THERE)
TOS = Address (HERE + 1)

CLRF **Clear f**

Syntax: [*label*] CLRF f,s

Operands: $0 \le f \le 255$

Operation: 00h → f, $s \in [0,1]$
00h → dest

Status Affected: None

Encoding:

0010	100s	ffff	ffff

Description: Clears the contents of the specified register(s).
s = 0: Data memory location 'f' and WREG are cleared.
s = 1: Data memory location 'f' is cleared.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write register 'f' and if specified WREG

Example: CLRF FLAG_REG, 1

Before Instruction
FLAG_REG = 0x5A
WREG = 0x01

After Instruction
FLAG_REG = 0x00
WREG = 0x01

MOVFP **Move f to p**

Syntax: [*label*] MOVFP f,p

Operands: $0 \le f \le 255$
$0 \le p \le 31$

Operation: (f) → (p)

Status Affected: None

Encoding:

011p	pppp	ffff	ffff

Description: Move data from data memory location 'f' to data memory location 'p'. Location 'f' can be anywhere in the 256 byte data space (00h to FFh), while 'p' can be 00h to 1Fh.

Either 'p' or 'f' can be WREG (a useful, special situation).

MOVFP is particularly useful for transferring a data memory location to a peripheral register (such as the transmit buffer or an I/O port). Both 'f' and 'p' can be indirectly addressed.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write register 'p'

Example: MOVFP REG1, REG2

Before Instruction
REG1 = 0x33,
REG2 = 0x11

After Instruction
REG1 = 0x33,
REG2 = 0x33

MOVLB **Move Literal to low nibble in BSR**

Syntax: [*label*] MOVLB k

Operands: $0 \le k \le 15$

Operation: k → (BSR<3:0>)

Status Affected: None

Encoding:

1011	1000	uuuu	kkkk

Description: The four-bit literal 'k' is loaded in the Bank Select Register (BSR). Only the low 4-bits of the Bank Select Register are affected. The upper half of the BSR is unchanged. The assembler will encode the “u” fields as '0'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write literal 'k' to BSR<3:0>

Example: MOVLB 5

Before Instruction
BSR register = 0x22

After Instruction
BSR register = 0x25 (Bank 5)

TABLE 19-1: DEVELOPMENT TOOLS FROM MICROCHIP

		PIC12CXXX	PIC14000	PIC16C5X	PIC16C6X	PIC16CXXX	PIC16F62X	PIC16C7X	PIC16C7XX	PIC16C8X	PIC16F8XX	PIC16C9XX	PIC17C4X	PIC17C7XX	PIC18CXX2	24CXX/ 25CXX/ 93CXX	HCSXXX	MCRFXXX	MCP2510
Software Tools	MPLAB® Integrated Development Environment	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓				
	MPLAB® C17 C Compiler												✓	✓					
	MPLAB® C18 C Compiler														✓				
	MPASM™ Assembler/ MPLINK™ Object Linker	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓		
Emulators	MPLAB® ICE In-Circuit Emulator	✓	✓	✓	✓	✓	✓**	✓	✓	✓	✓	✓	✓	✓	✓				
	ICEPIC™ In-Circuit Emulator	✓		✓	✓	✓		✓	✓	✓		✓							
Debugger	MPLAB® ICD In-Circuit Debugger				✓*			✓*			✓								
Programmers	PICSTART® Plus Entry Level Development Programmer	✓	✓	✓	✓	✓	✓**	✓	✓	✓	✓	✓	✓	✓	✓				
	PRO MATE® II Universal Device Programmer	✓	✓	✓	✓	✓	✓**	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓		
Demo Boards and Eval Kits	PICDEM™ 1 Demonstration Board			✓		✓		✓†		✓			✓						
	PICDEM™ 2 Demonstration Board				✓†			✓†							✓				
	PICDEM™ 3 Demonstration Board											✓							
	PICDEM™ 14A Demonstration Board		✓																
	PICDEM™ 17 Demonstration Board													✓					
	KEELOQ® Evaluation Kit																✓		
	KEELOQ® Transponder Kit																✓		
	microID™ Programmer's Kit																	✓	
	125 kHz microID™ Developer's Kit																	✓	
	125 kHz Anticollision microID™ Developer's Kit																	✓	
	13.56 MHz Anticollision microID™ Developer's Kit																	✓	
	MCP2510 CAN Developer's Kit																		✓

* Contact the Microchip Technology Inc. web site at www.microchip.com for information on how to use the MPLAB® ICD In-Circuit Debugger (DV164001) with PIC16C62, 63, 64, 65, 72, 73, 74, 76, 77.
** Contact Microchip Technology Inc. for availability date.
† Development tool is available on select devices.

20.2 DC Characteristics: PIC17C7XX-16 (Commercial, Industrial, Extended) PIC17C7XX-33 (Commercial, Industrial, Extended) PIC17LC7XX-08 (Commercial, Industrial)

DC CHARACTERISTICS			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +125°C for extended -40°C ≤ TA ≤ +85°C for industrial 0°C ≤ TA ≤ +70°C for commercial Operating voltage VDD range as described in Section 20.1				
Param. No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
		Input Low Voltage					
	VIL	I/O ports					
D030		with TTL buffer **(Note 6)**	Vss	–	0.8	V	4.5V ≤ VDD ≤ 5.5V
			Vss	–	0.2VDD	V	3.0V ≤ VDD ≤ 4.5V
D031		with Schmitt Trigger buffer					
		RA2, RA3	Vss	–	0.3VDD	V	I^2C compliant
		All others	Vss	–	0.2VDD	V	
D032		$\overline{MCLR}$, OSC1 (in EC and RC mode)	Vss	–	0.2VDD	V	**(Note 1)**
D033		OSC1 (in XT, and LF mode)	–	0.5VDD	–	V	
		Input High Voltage					
	VIH	I/O ports					
D040		with TTL buffer **(Note 6)**	2.0	–	VDD	V	4.5V ≤ VDD ≤ 5.5V
			1 + 0.2VDD	–	VDD	V	3.0V ≤ VDD ≤ 4.5V
D041		with Schmitt Trigger buffer					
		RA2, RA3	0.7VDD	–	VDD	V	I^2C compliant
		All others	0.8VDD	–	VDD	V	
D042		$\overline{MCLR}$	0.8VDD	–	VDD	V	**(Note 1)**
D043		OSC1 (XT, and LF mode)	–	0.5VDD	–	V	
D050	VHYS	**Hysteresis of Schmitt Trigger Inputs**	0.15VDD	–	–	V	

† Data in "Typ" column is at 5V, 25°C unless otherwise stated.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC17CXXX devices be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. Higher leakage current may be measured at different input voltages.

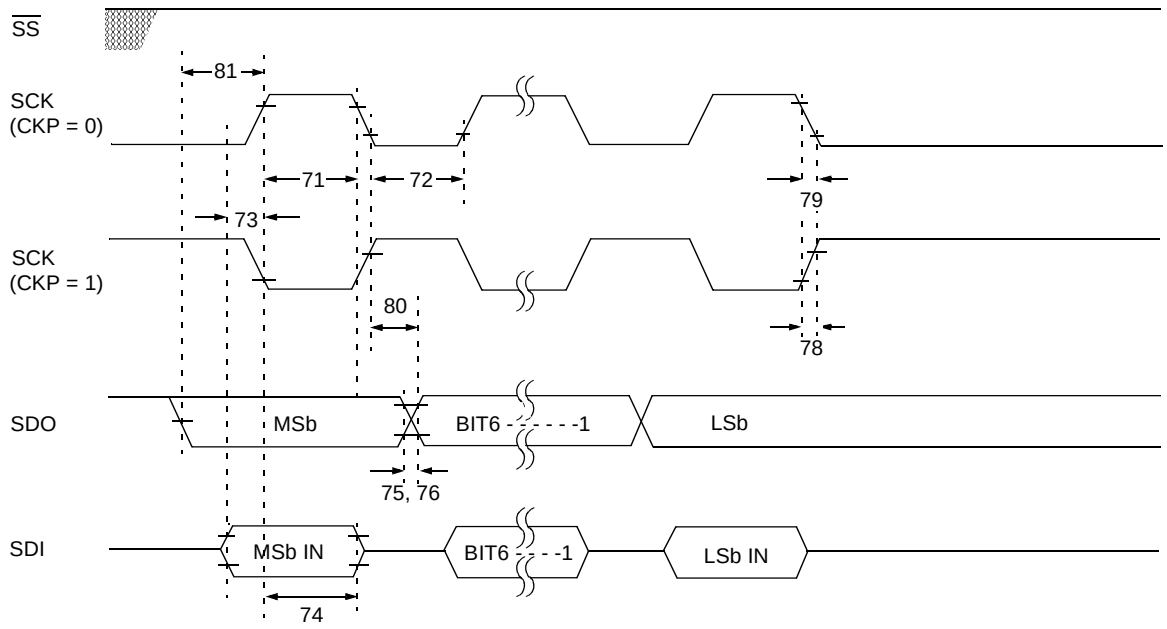
3: Negative current is defined as current sourced by the pin.

4: These specifications are for the programming of the on-chip program memory EPROM through the use of the table write instructions. The complete programming specifications can be found in: PIC17C7XX Programming Specifications (Literature number DS TBD).

5: The $\overline{MCLR}$/VPP pin may be kept in this range at times other than programming, but is not recommended.

6: For TTL buffers, the better of the two specifications may be used.

FIGURE 20-14: SPI MASTER MODE TIMING (CKE = 1)



Note: Refer to Figure 20-5 for load conditions.

TABLE 20-9: SPI MODE REQUIREMENTS (MASTER MODE, CKE = 1)

Param. No.	Symbol	Characteristic		Min	Typ†	Max	Units	Conditions
71	TscH	SCK input high time (Slave mode)	Continuous	1.25TCY + 30	—	—	ns	
71A			Single Byte	40	—	—	ns	**(Note 1)**
72	TscL	SCK input low time (Slave mode)	Continuous	1.25 TCY + 30	—	—	ns	
72A			Single Byte	40	—	—	ns	**(Note 1)**
73	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge		100	—	—	ns	
73A	TB2B	Last clock edge of Byte1 to the 1st clock edge of Byte2		1.5TCY + 40	—	—	ns	**(Note 1)**
74	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge		100	—	—	ns	
75	TdoR	SDO data output rise time		—	10	25	ns	
76	TdoF	SDO data output fall time		—	10	25	ns	
78	TscR	SCK output rise time (Master mode)		—	10	25	ns	
79	TscF	SCK output fall time (Master mode)		—	10	25	ns	
80	TscH2doV, TscL2doV	SDO data output valid after SCK edge		—	—	50	ns	
81	TdoV2scH, TdoV2scL	SDO data output setup to SCK edge		Tcy	—	—	ns	

† Data in "Typ" column is at 5V, 25°C unless otherwise stated.

Note 1: Specification 73A is only required if specifications 71A and 72A are used.

TABLE 20-18: A/D CONVERTER CHARACTERISTICS

Param. No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
A01	NR	Resolution		—	—	10	bit	VREF+ = VDD = 5.12V, VSS ≤ VAIN ≤ VREF+
				—	—	10	bit	(VREF+ — VREF-) ≥ 3.0V, VREF- ≤ VAIN ≤ VREF+
A02	EABS	Absolute error		—	—	< ±1	LSb	VREF+ = VDD = 5.12V, VSS ≤ VAIN ≤ VREF+
				—	—	< ±1	LSb	(VREF+ — VREF-) ≥ 3.0V, VREF- ≤ VAIN ≤ VREF+
A03	EIL	Integral linearity error		—	—	< ±1	LSb	VREF+ = VDD = 5.12V, VSS ≤ VAIN ≤ VREF+
				—	—	< ±1	LSb	(VREF+ — VREF-) ≥ 3.0V, VREF- ≤ VAIN ≤ VREF+
A04	EDL	Differential linearity error		—	—	< ±1	LSb	VREF+ = VDD = 5.12V, VSS ≤ VAIN ≤ VREF+
				—	—	< ±1	LSb	(VREF+ — VREF-) ≥ 3.0V, VREF- ≤ VAIN ≤ VREF+
A05	EFS	Full scale error		—	—	< ±1	LSb	VREF+ = VDD = 5.12V, VSS ≤ VAIN ≤ VREF+
				—	—	< ±1	LSb	(VREF+ — VREF-) ≥ 3.0V, VREF- ≤ VAIN ≤ VREF+
A06	EOFF	Offset error		—	—	< ±1	LSb	VREF+ = VDD = 5.12V, VSS ≤ VAIN ≤ VREF+
				—	—	< ±1	LSb	(VREF+ — VREF-) ≥ 3.0V, VREF- ≤ VAIN ≤ VREF+
A10	—	Monotonicity		—	guaranteed(3)	—	—	VSS ≤ VAIN ≤ VREF
A20	VREF	Reference voltage (VREF+ — VREF-)		0V	—	—	V	VREF delta when changing voltage levels on VREF inputs
A20A				3V	—	—	V	Absolute minimum electrical spec. to ensure 10-bit accuracy
A21	VREF+	Reference voltage high		AVSS + 3.0V	—	AVDD + 0.3V	V	
A22	VREF-	Reference voltage low		Avss - 0.3V	—	AVDD - 3.0V	V	
A25	VAIN	Analog input voltage		AVSS - 0.3V	—	Vref + 0.3V	V	
A30	ZAIN	Recommended impedance of analog voltage source		—	—	10.0	kΩ	
A40	IAD	A/D conversion current (VDD)	PIC17**C**XXX	—	180	—	μA	Average current consumption when A/D is on **(Note 1)**
			PIC17**LC**XXX	—	90	—	μA	
A50	IREF	VREF input current **(Note 2)**		10	—	1000	μA	During VAIN acquisition. Based on differential of VHOLD to VAIN
				—	—	10	μA	During A/D conversion cycle

† Data in "Typ" column is at 5V, 25°C unless otherwise stated.

Note 1: When A/D is off, it will not consume any current other than minor leakage current. The power-down current spec includes any such leakage from the A/D module.

2: VREF current is from RG0 and RG1 pins or AVDD and AVSS pins, whichever is selected as reference input.

3: The A/D conversion result never decreases with an increase in the Input Voltage and has no missing codes.